

N-Channel Trench Power MOSFET

 Lead Free Package and Finish

General Description

The RS30N100G uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 5V. This device is suitable for use as a wide variety of applications.

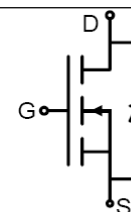
Features

- $V_{DS} = 30V, I_D = 100A$
 $R_{DS(ON)} < 3.2m\Omega @ V_{GS} = 10V$
 $R_{DS(ON)} < 6m\Omega @ V_{GS} = 5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

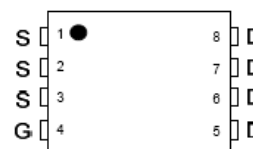
Application

- PWM applications
- DC/DC Converters
- Power management

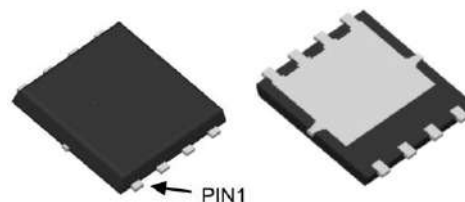
100% UIS TESTED!
100% ΔV_d s TESTED!



Schematic Diagram



Pin Assignment



DFN5X6-8L top&bottom view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|-----------|----------------|-----------|------------|----------|
| RS30N100G | RS30N100G | DFN5X6-8L | - | - | - |

Table 1. Absolute Maximum Ratings ($T_A=25^\circ C$)

| Symbol | Parameter | Value | Unit |
|------------------|---------------------------------------------------|------------|------------|
| V_{DS} | Drain-Source Voltage ($V_{GS}=0V$) | 30 | V |
| V_{GS} | Gate-Source Voltage ($V_{DS}=0V$) | ± 20 | V |
| I_D | Drain Current-Continuous($T_c=25^\circ C$) | 100 | A |
| | Drain Current-Continuous($T_c=100^\circ C$) | 69 | A |
| $I_{DM (pluse)}$ | Drain Current-Continuous@ Current-Pulsed (Note 1) | 400 | A |
| P_D | Maximum Power Dissipation($T_c=25^\circ C$) | 58 | W |
| | Maximum Power Dissipation($T_c=100^\circ C$) | 23 | W |
| E_{AS} | Avalanche energy (Note 2) | 870 | mJ |
| T_J, T_{STG} | Operating Junction and Storage Temperature Range | -55 To 150 | $^\circ C$ |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 2.EAS condition: $T_J=25^\circ C, V_{DD}=20V, V_G=10V, R_G=25\Omega$

Table 2. Thermal Characteristic

| Symbol | Parameter | Typ | Max | Unit |
|-----------------|--------------------------------------|-----|------|--------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | - | 2.15 | $^\circ C/W$ |

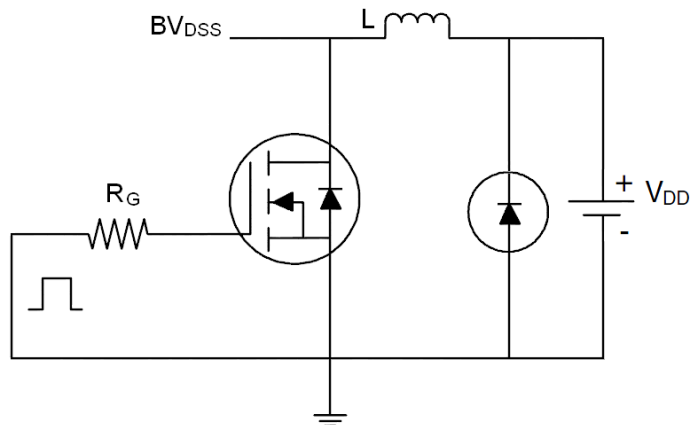
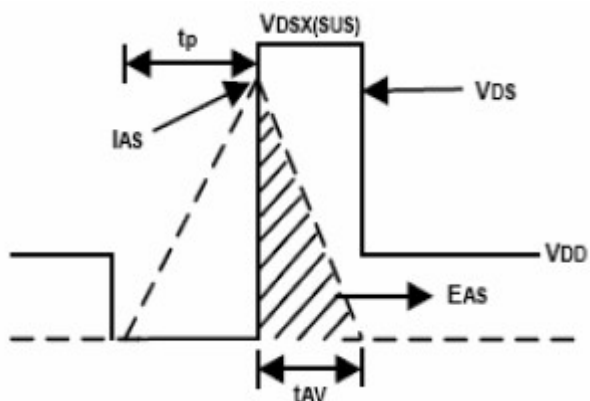
Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------------------|----------------------------------------|--------------------------------------------------------------------------------------------|-----|------|------|------|
| On/Off States | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 30 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =24V, V _{GS} =0V | | | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±20V, V _{DS} =0V | | | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1 | 1.6 | 3 | V |
| g _{FS} | Forward Transconductance | V _{DS} =5V, I _D =20A | 18 | 45 | | S |
| R _{DS(ON)} | Drain-Source On-State Resistance | V _{GS} =10V, I _D =20A | | 2.3 | 3.2 | mΩ |
| | | V _{GS} =5V, I _D =20A | | 4 | 6 | mΩ |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} =15V, V _{GS} =0V, f=1.0MHz | | 5400 | | pF |
| C _{oss} | Output Capacitance | | | 920 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 260 | | pF |
| R _g | Gate resistance | V _{GS} =0V, V _{DS} =0V, f=1.0MHz | | 0.9 | | Ω |
| Switching Times | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{GS} =10V, V _{DS} =15V, R _L =0.75Ω, R _{GEN} =3Ω | | 24 | | nS |
| t _r | Turn-on Rise Time | | | 49 | | nS |
| t _{d(off)} | Turn-Off Delay Time | | | 85 | | nS |
| t _f | Turn-Off Fall Time | | | 21 | | nS |
| Q _g | Total Gate Charge | V _{GS} =10V, V _{DS} =25V, I _D =14A | | 126 | | nC |
| Q _{gs} | Gate-Source Charge | | | 14 | | nC |
| Q _{gd} | Gate-Drain Charge | | | 38 | | nC |
| Source-Drain Diode Characteristics | | | | | | |
| I _{SD} | Source-Drain Current(Body Diode) | | | | 100 | A |
| V _{SD} | Forward on Voltage ^(Note 1) | V _{GS} =0V, I _S =20A | | | 1.2 | V |
| t _{rr} | Body Diode Reverse Recovery Time | I _F =20A, dI/dt=100A/μs | | 29 | | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | I _F =20A, dI/dt=100A/μs | | 20 | | nC |

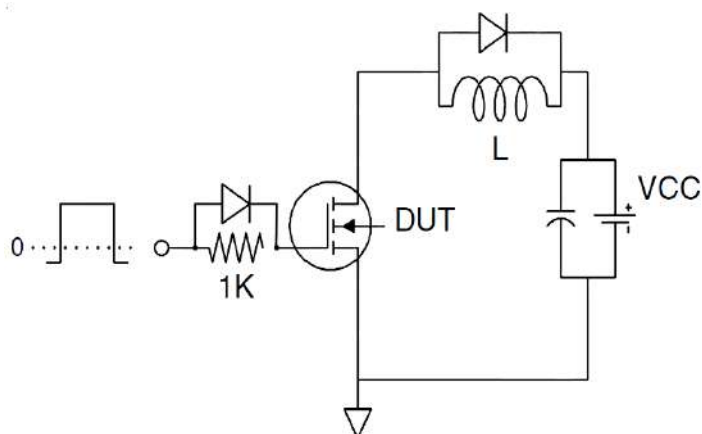
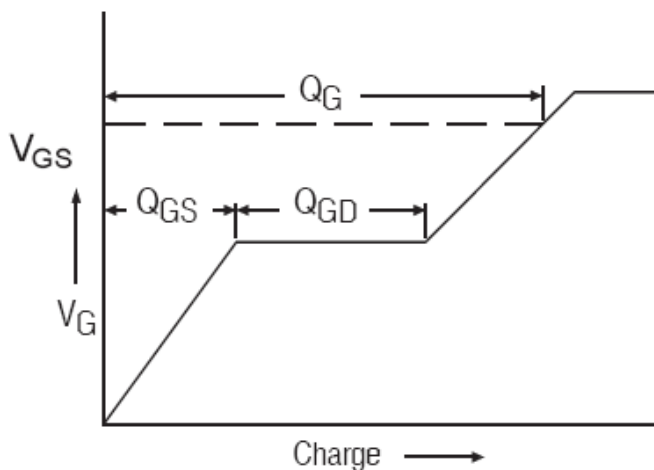
Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Test Circuit

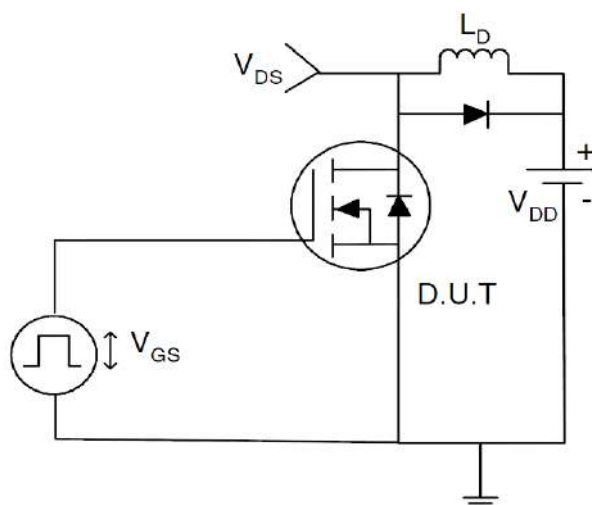
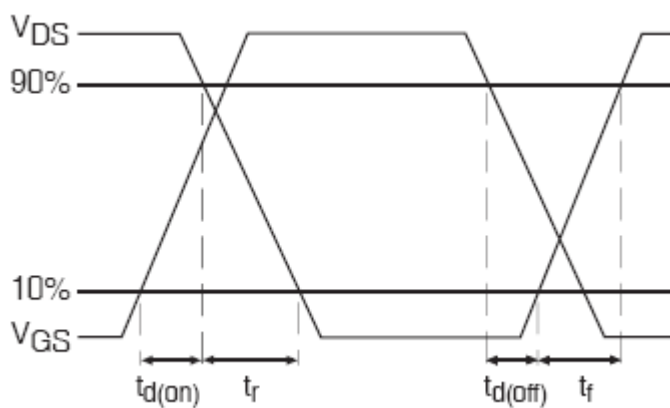
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure 1. Output Characteristics

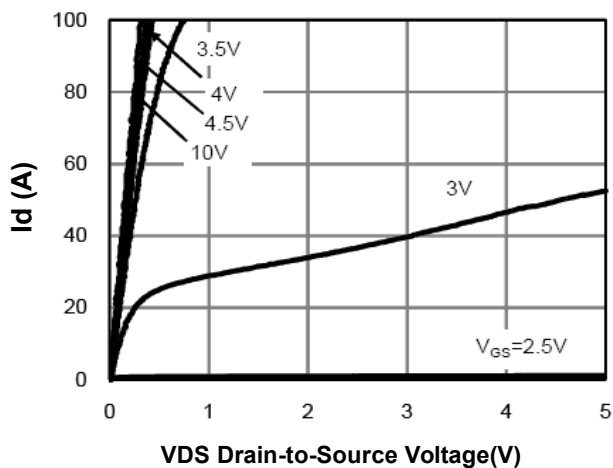


Figure 2. Transfer Characteristics

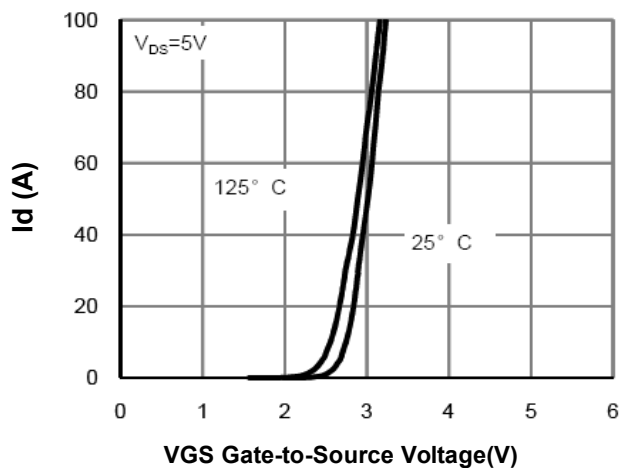


Figure 3. Max BV_{DSS} vs Junction Temperature

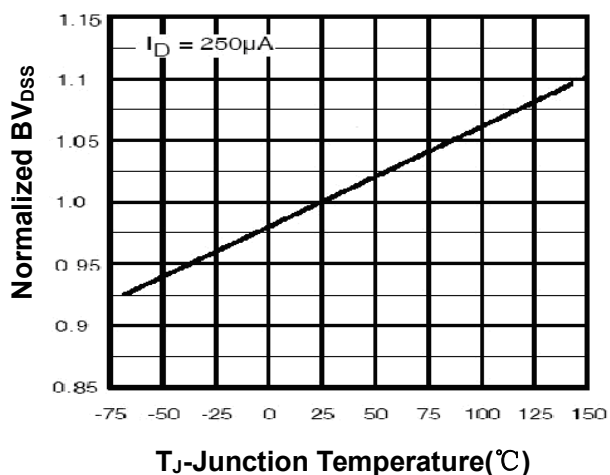


Figure 4. Drain Current

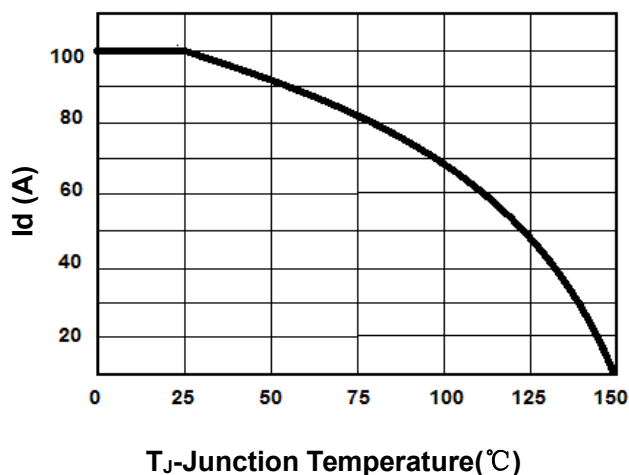


Figure 5. $V_{GS(th)}$ vs Junction Temperature

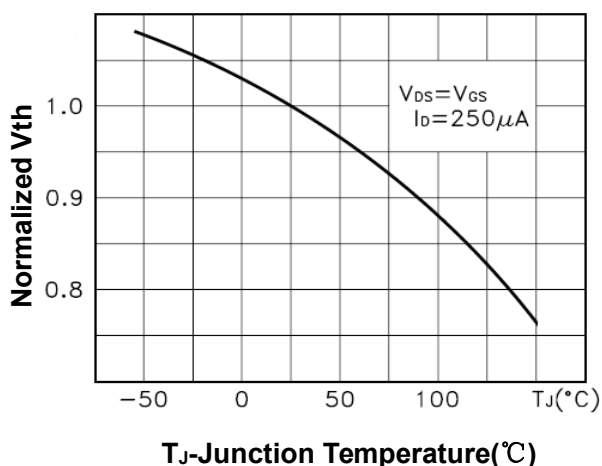


Figure 6. $R_{DS(on)}$ vs Junction Temperature

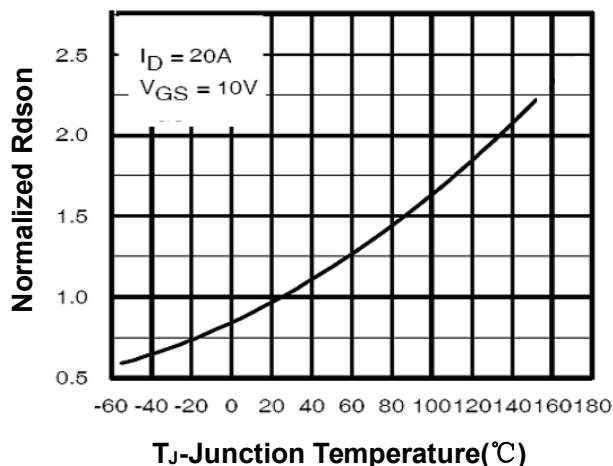


Figure 7. Gate Charge Waveforms

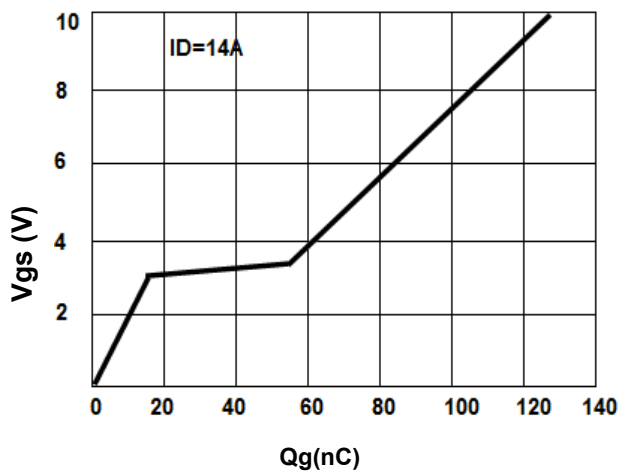


Figure 8. Capacitance

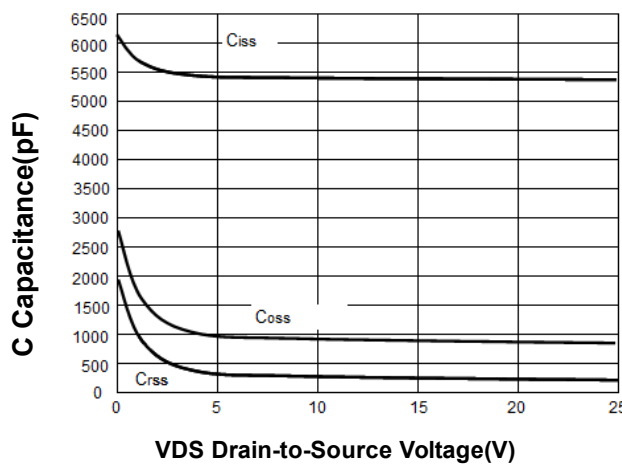


Figure 9. Body-Diode Characteristics

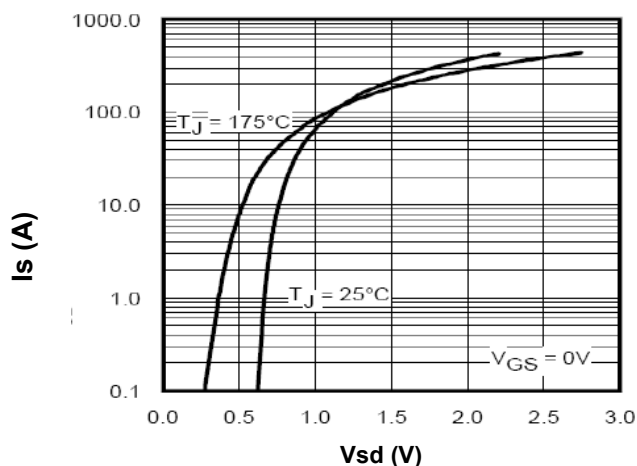


Figure 10. Maximum Safe Operating Area

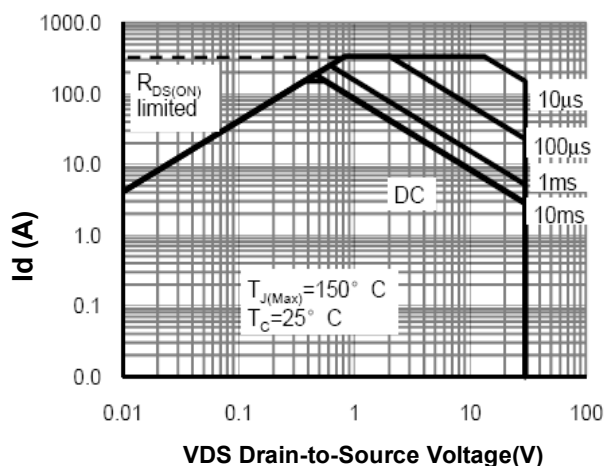
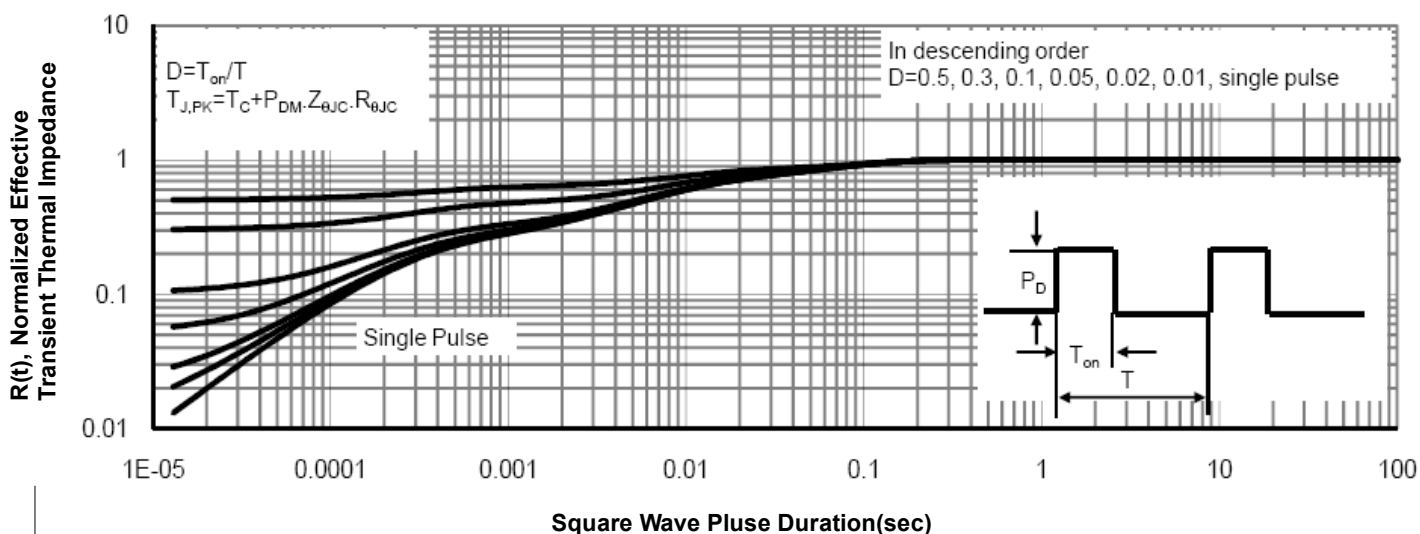
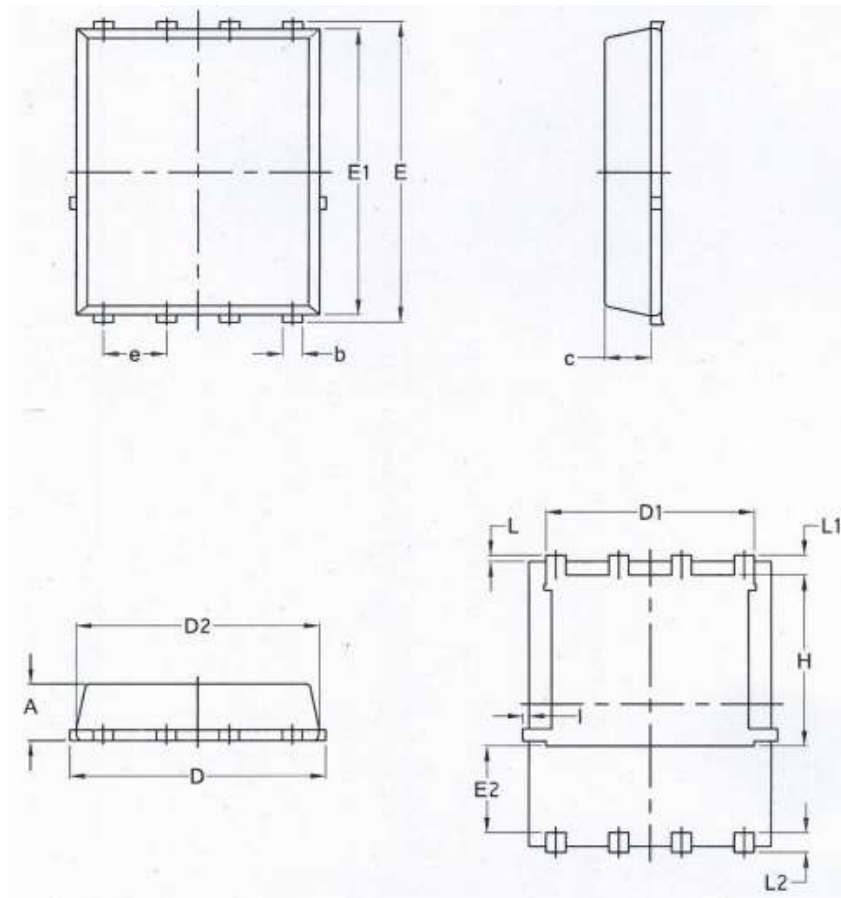


Figure 11. Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



| SYMBOL | COMMON | | | |
|--------|----------|-------|----------|--------|
| | MM | | INCH | |
| | MIN. | MAX. | MIN. | MAX. |
| A | 1.03 | 1.17 | 0.0406 | 0.0461 |
| b | 0.34 | 0.48 | 0.0134 | 0.0189 |
| c | 0.824 | 0.970 | 0.0324 | 0.0382 |
| D | 4.80 | 5.40 | 0.1890 | 0.2126 |
| D1 | 4.11 | 4.31 | 0.1618 | 0.1697 |
| D2 | 4.80 | 5.00 | 0.1890 | 0.1969 |
| E | 5.95 | 6.15 | 0.2343 | 0.2421 |
| E1 | 5.65 | 5.85 | 0.2224 | 0.2303 |
| E2 | 1.60 | — | 0.0630 | — |
| e | 1.27 BSC | | 0.05 BSC | |
| L | 0.05 | 0.25 | 0.0020 | 0.0098 |
| L1 | 0.38 | 0.50 | 0.0150 | 0.0197 |
| L2 | 0.38 | 0.50 | 0.0150 | 0.0197 |
| H | 3.30 | 3.50 | 0.1299 | 0.1378 |
| l | — | 0.18 | — | 0.0070 |